



## **SPECIFICATION**

- · Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- · Samsung P/N :
- CL03A333KQ3NNNH

(Reference sheet)

- · Description :
- CAP, 33nF, 6.3V, ±10%, X5R, 0201

A. Samsung Part Number

		<u>CL</u>	<u>03</u> ②	<mark>4</mark> 3	<u>333</u> ④	<u>K</u> 5	<mark>Q</mark> 6	<u>3</u> 7	<u>N</u> 8	<u>N</u> 9	<u>N</u> 10	<mark>Н</mark> Ш
1	Series	Samsung Multi-layer Ceramic Capacitor										
2	Size	0201 (inch o	code)		L:	0.60	± 0.03	mm			W:	$0.30 \pm 0.03$ mm
3	Dielectric	X5R				8	Inner	elect	rode			Ni
4	Capacitance	33 nF					Term	inatio	n			Cu
5	Capacitance	±10 %					Platir	ıg				Sn 100% (Pb Free)
	tolerance					9	Prod	uct				Normal
6	Rated Voltage	6.3 V				10	Spec	ial				Reserved for future use
1	Thickness	$0.30 \pm 0.03$ mm				1	Packa	aging				Cardboard Type, 7" reel

## **B. Structure & Dimension**



Samsung P/N	Dimension(mm)							
Samsung F/N	L	W	Т	BW				
CL03A333KQ3NNNH	0.60 ± 0.03	0.30 ± 0.03	0.30 ± 0.03	0.15 ± 0.05				

## C. Samsung Reliablility Test and Judgement Condition

Tan δ (DF)   Insulation 10,   Resistance With   Appearance No	thin specified tolerance 0.1 max. 000Mohm or 100Mohm×µF hichever is smaller abnormal exterior appearance dielectric breakdown or	1 <sup>klt</sup> ±10% / 1.0±0.2Vrms *A capacitor prior to measuring the capacitance is heat treated at 150°C+0/-10°C for 1 hour and maintained in ambient air for 24±2 hours. Rated Voltage 60~120 sec.				
Insulation 10, Resistance Wi Appearance No	000Mohm or 100Mohm× <i>µ</i> F hichever is smaller abnormal exterior appearance	treated at 150°C+0/-10°C for 1 hour and maintained in ambient air for 24±2 hours. Rated Voltage 60~120 sec.				
ResistanceWithAppearanceNo	hichever is smaller abnormal exterior appearance					
Appearance No	abnormal exterior appearance					
Withstanding	dielectric breakdown or	Microscope (×10)				
		250% of the rated voltage				
Voltage me	chanical breakdown					
Temperature X5F	R					
Characteristics (Fro	om-55℃ to 85℃, Capacitance change sho	ould be within ±15%)				
Adhesive Strength No	peeling shall be occur on the	200g·f, for 10±1 sec.				
of Termination terr	minal electrode					
Bending Strength Cap	pacitance change : within ±12.5%	Bending to the limit (1mm)				
		with 1.0mm/sec.				
Solderability Mo	re than 75% of terminal surface	SnAg3.0Cu0.5 solder				
is to	o be soldered newly	245±5℃, 3±0.3sec.				
		(preheating : 80~120℃ for 10~30sec.)				
Resistance to Cap	pacitance change : within ±7.5%	Solder pot : 270±5℃, 10±1sec.				
	n δ, IR : initial spec.					
	pacitance change : within ± 5% η δ, IR : initial spec.	Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) 2hours × 3 direction (x, y, z)				
Moisture Car	pacitance change : within ±12.5%	With rated voltage				
Resistance Tar	nδ: 0.125 max	40±2℃, 90~95%RH, 500+12/-0hrs				
IR :	500Mohm or 12.5Mohm × $\mu$ F					
	Whichever is smaller					
High Temperature Cap	pacitance change : within ±12.5%	With 150% of the rated voltage				
	ηδ: 0.125 max	Max. operating temperature				
IR :	1,000Mohm or 25Mohm × $\mu$ F	1000+48/-0hrs				
	Whichever is smaller					
Temperature Cap	pacitance change : within ±7.5%	1 cycle condition				
	η δ, IR : initial spec.	Min. operating temperature $\rightarrow$ 25°C				
		→ Max. operating temperature → $25^{\circ}$ C				
		5 cycle test				

X The reliability test condition can be replaced by the corresponding accelerated test condition.

## D. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5°C, 10sec. Max )

Product specifications included in the specifications are effective as of March 1, 2013. Please be advised that they are standard product specifications for reference only. We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.